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12	APPL NUM 10056256	FILING DATE 01/24/2002	CLASS 257	SUBCLASS 2841	GAU 2827	EXAMINER WAN TIA	
<p>**APPLICANTS: Blackshear Edmund; Beausoleil William; Tomassetti N.; 2827</p> <p>**CONTINUING DATA VERIFIED:</p> <p>** FOREIGN APPLICATIONS VERIFIED:</p>							
PG-PUB		<input type="checkbox"/> DO NOT PUBLISH		<input type="checkbox"/> RESCIND			
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no 35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no Verified and Acknowledged Examiner's initials				ATTORNEY DOCKET NO FIS9-2000-0273US1			
TITLE : Vertically stacked memory chips in FBGA packages							
U.S. DEPT. OF COMM./PAT. & TM-PTO-436L(Rev. 12-94)							

NOTICE OF ALLOWANCE MAILED		Assistant Examiner	CLAIMS ALLOWED		
			Total Claims	Print Claim for O.G.	
ISSUE FEE			DRAWING		
Amount Due	Date Paid		Sheets Drwg.	Figs.Drwg.	Print Fig.
		Primary Examiner			
		PREPARED FOR ISSUE	Application Examiner		
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